

TEWA TEMPERATURE SENSORS

HIGH PRECISION NTC THERMISTORS AND TEMPERATURE SENSORS

DECLARATION OF COMPLIANCE - RoHS Declaration -

Applies to products launched by TEWA Temperature Sensors Ltd. Lublin, Poland

Tewa Temperature Sensors, Poland declares that its products (including subcomponents as thermistors, cables, resin and others) are designed to be:

- RoHS compliant and meet the requirements defined under Directive 2011/65/EU of the European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) – recast and its amendments: Commission Delegated Directive (EU) 2015/863 of 31 March 2015 which becomes effective from 22 July 2019.

| RoHS Restricted Substance | Allowable Limit |
|--|-------------------------|
| Cadmium and its compounds | 100 ppm (0.01 weight %) |
| Mercury and its compounds | 1000 ppm (0.1 weight %) |
| Hexavalent chromium and its compounds | 1000 ppm (0.1 weight %) |
| Lead and its compounds | 1000 ppm (0.1 weight %) |
| Polybrominated biphenyls (PBB) | 1000 ppm (0.1 weight %) |
| Polybrominated diphenyl ethers (PBDE)* | 1000 ppm (0.1 weight %) |
| Bis(2-ethylhexyl) phthalate (DEHP)** | 1000 ppm (0.1 weight %) |
| Butyl benzyl phthalate (BBP)** | 1000 ppm (0.1 weight %) |
| Dibutyl phthalate (DBP)** | 1000 ppm (0.1 weight %) |
| Diisobutyl phthalate (DIBP)** | 1000 ppm (0.1 weight %) |

Tewa RoHS compliant temperature sensors and thermistors contain no more than 0.1% lead (Pb) by weight per homogeneous material, or may contain lead (Pb) for uses allowed by the RoHS Directive, as amended. Tewa might use any of the following RoHS exemptions for RoHS compliant products:

| RoHS Exemption | RoHS Exemption Description |
|----------------|--|
| 7(a) | Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) |
| 7(c)-I | Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound |
| 15 | Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages |

In determining the RoHS status of its products, Tewa Temperature Sensors Poland relies upon its suppliers' material content data certification for each homogenous material in the product(s) that they or their subcontractors provide. The signature below verifies that statements above, including but not limited to material composition data are valid and accurate to the best of our knowledge for Tewa products in original sale condition.

Lech Wojtachnia



Quality Manager

DATE: 14/03/2019